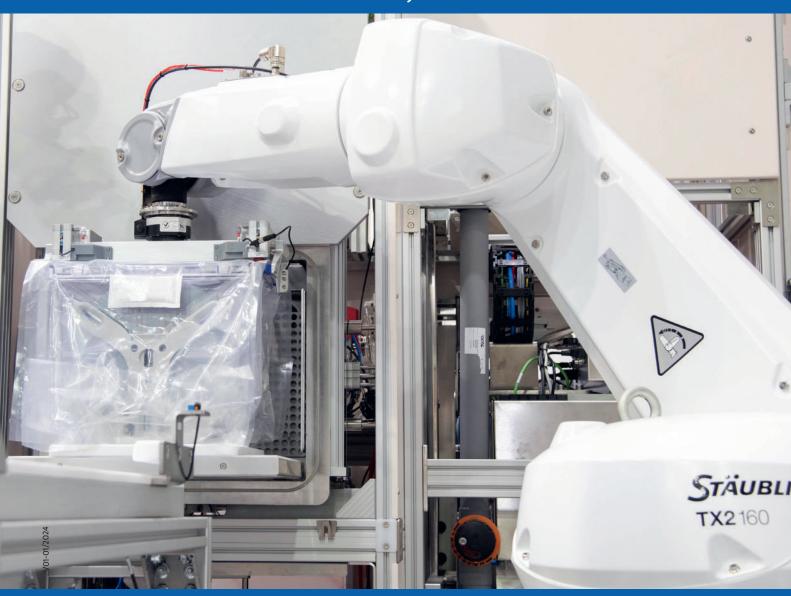


FULLY AUTOMATIC SOLUTION FOR FOSB PACKAGING

Fully automatic. Safe. Efficient.



The autobagging tool: Fully automatic packaging of FOSBs

The packaging of wafers for transportation to a semiconductor plant (FAB) is a complex process and is subject to the strictest criteria. We have fully automated the packaging process! Our AutoBagging Tool (ABT) significantly increases throughput and offers a considerable increase in quality and safety during packaging. The throughput is 3,000 to 8,000 FOSB/month (75k to 200k wafers/month).

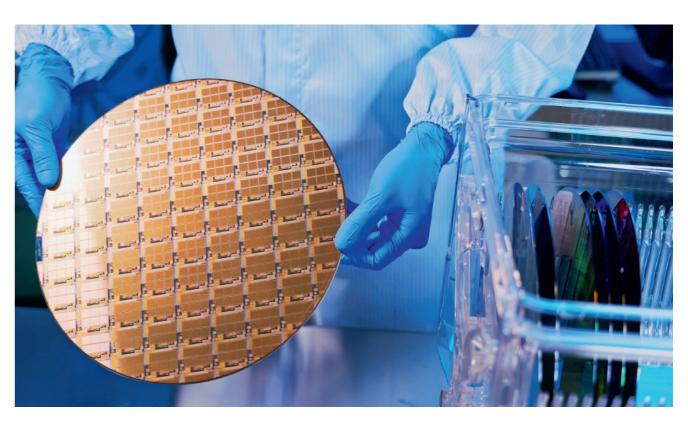
The advantages at a glance:

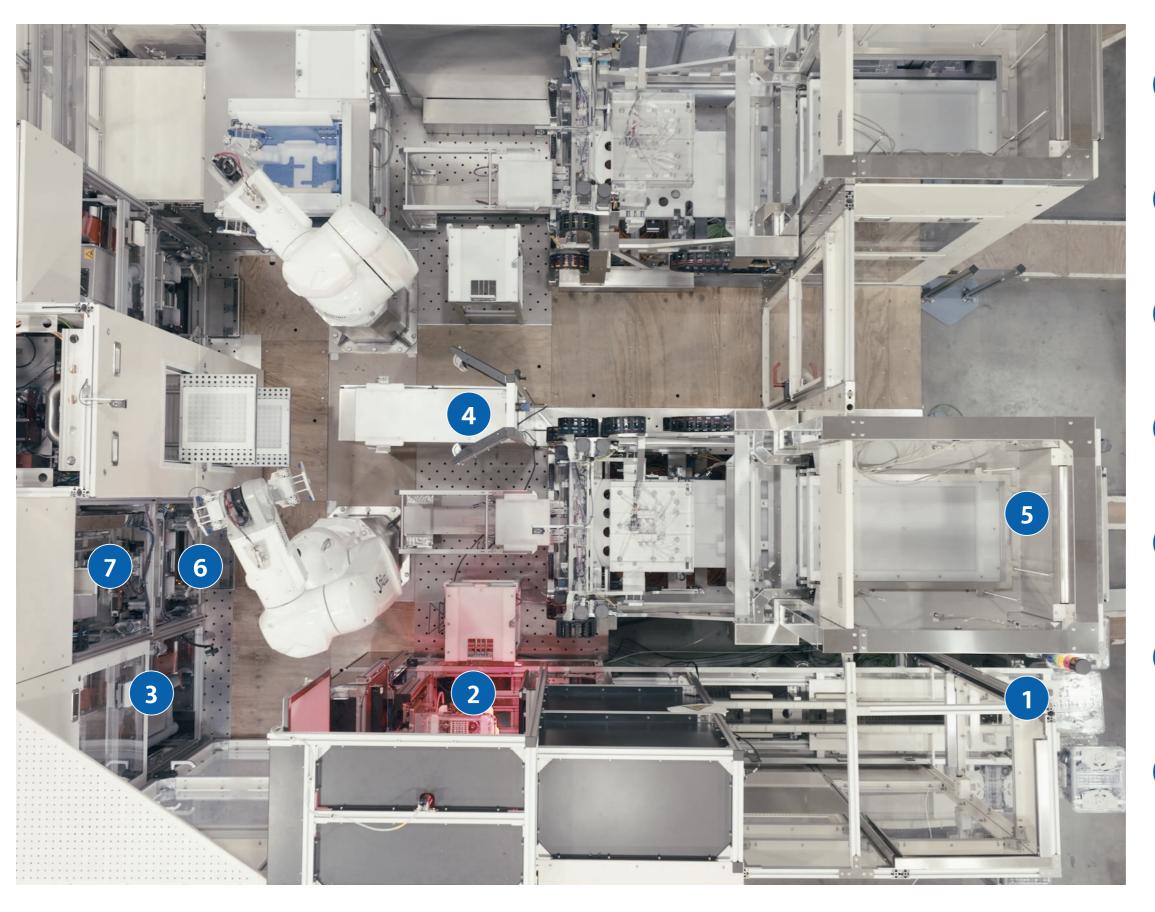
- Increase in efficiency
- Significant reduction in the error rate
- Increase in quality
- Reduced workload for employees
- Usually no set-up time required

The packaging machine, the test chamber, the robots and all other components are placed in a complete cell. This has an infeed conveyor for the unpackaged FOSBs and an outfeed conveyor for the packaged FOSBs. Various checks (cross-slot, fill level, attachments) as well as labeling (including checking the print) and folding/gluing the bags are carried out entirely in the ABT.

Numerous checks guarantee a safe packaging process:

- Cross-Slot-Check
- Attachment testing
- Checking all applied labels (quality and content)
- 100% Leak test



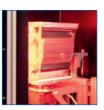






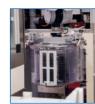
Infeed belt
Feeding of the unpacked
FOSBs by OHT, AMR or
operator





ReviewCross-Slot-Check and
Attachment testing





Labeling FOSB





Quality check of the label





Packing and sealing inner bags





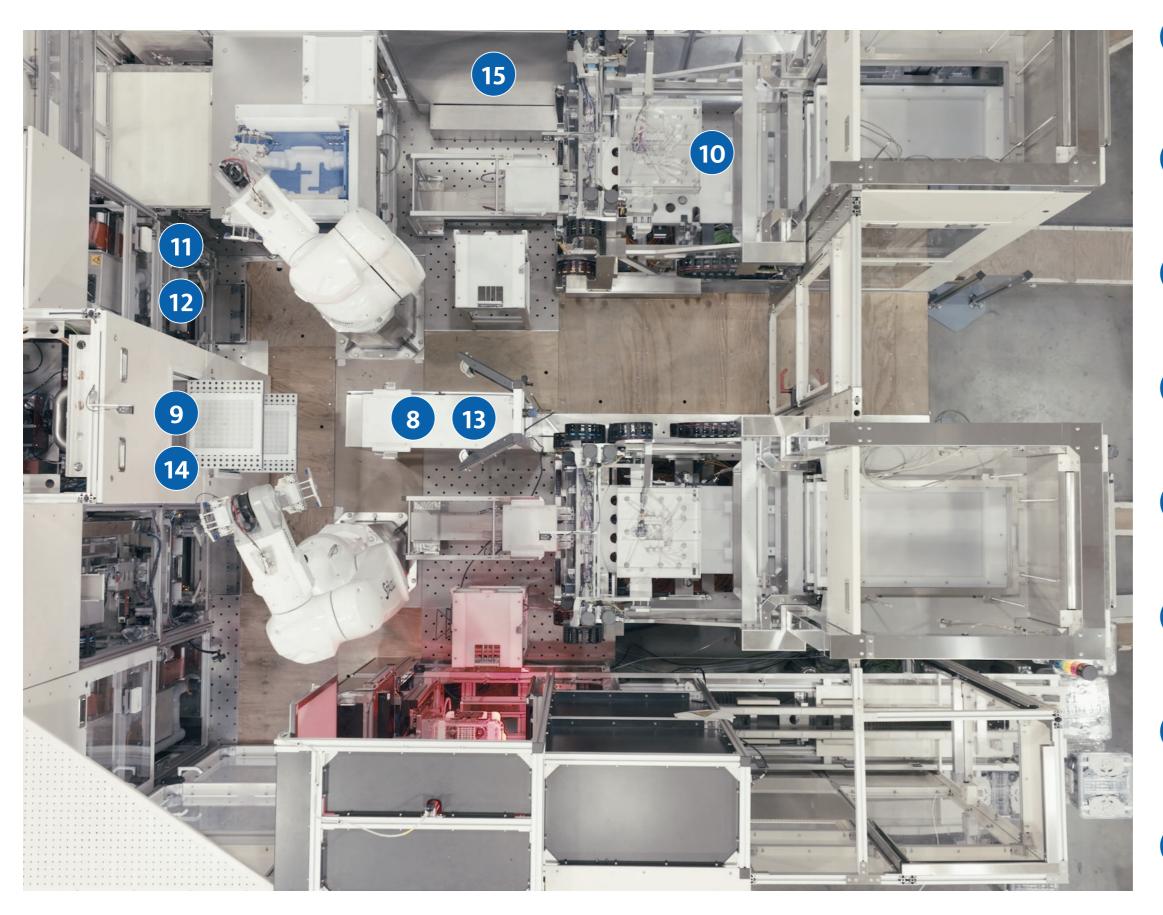
Folding and sticking the overhang





Labeling inner bag, attach desiccant bag

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Quality check of the label





Leak test with test gas





Pack and seal in outer bag





Folding and sticking outer bag





Labeling outer bag





Quality check of the label





Leak test with test gas





Extraction

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